

Parker Chomerics CHO-BOND 1085 Conductive Adhesive

Category : Polymer , Adhesive , Thermoset

Material Notes:

CHO-BOND® adhesives are electrically conductive epoxy and silicone resins. Curing mechanisms are either room temperature, elevated temperature or moisture. Both single and two-component systems are available, depending on the resin system selected. Information provided by Chomerics

Order this product through the following link:

http://www.lookpolymers.com/polymer_Parker-Chomerics-CHO-BOND-1085-Conductive-Adhesive.php

Physical Properties	Metric	English	Comments
Specific Gravity	0.720 - 1.02 g/cc	0.720 - 1.02 g/cc	
Thickness	<= 5.08 microns	<= 0.200 mil	

Thermal Properties	Metric	English	Comments
Maximum Service Temperature, Air	200 °C	392 °F	
Minimum Service Temperature, Air	-80.0 °C	-112 °F	

Processing Properties	Metric	English	Comments
Cure Time	30.0 min @Temperature 23.0 °C	0.500 hour @Temperature 73.4 °F	
Shelf Life	6.00 Month	6.00 Month	

Descriptive Properties	Value	Comments
Binder	Primer	
Consistency	Thin Fluid	
Filler	Primer	
Mix Ratio	1-part	

Contact Songhan Plastic Technology Co.,Ltd.

Website : www.lookpolymers.comEmail : sales@lookpolymers.com

Tel : +86 021-51131842

Mobile : +86 13061808058

Skype : lookpolymers

Address : United North Road 215, Fengxian District, Shanghai City, China